

ABSTRACT

5 Mechanism for exchanging chip-carrier plates, in particular for
use in a hybrid chip-bonding machine (1), with: a plurality of
chip-carrier plates (12), a magazine (10) to store the
plurality of chip-carrier plates (12), a transport arrangement
10 (40) comprising a first and second clamping device (42, 44)
that are disposed on a movable holder (46), such that the
transport arrangement is designed to remove a selected chip-
carrier plate from the magazine, deliver it to a processing
station, in particular a chip-detaching system (8), of the
15 chip-bonding machine, and after processing remove it from the
processing station and deposit it in the magazine, a control
means to move the chip-carrier plates within the magazine in
such a way that the selected chip-carrier plate is positioned
at a collection point to be collected from the magazine, and a
20 control means to move the holder of the transport arrangement,
wherein the first and second clamping devices (42, 44) are
disposed one above the other, in particular in a vertical
arrangement, on the holder (46) and are constructed so that
each can individually release or grip a chip-carrier plate in
25 one and the same angular position of the holder.

(Fig. 1)